Stack-up and Viaspans

Board Type Rigid **Board struture** Standard **Materials** None

Layers 10 **Laminations** 1

RIGID PART Total Thickness 1.680 mm

#	Definition	Type	Thickness
	Soldermask	SM = 0,015 mm	0.015
1	Copper	CU 35 um	0.035
	Prepreg	PP FR4 = 0,100 mm	0.1
2	Copper	CU 35 um	0.035
	CORE	IL 0,20	0.2
3	Copper	CU 35 um	0.035
	Prepreg	PP FR4 = 0,100 mm	0.1
4	Copper	CU 35 um	0.035
	CORE	IL 0,20	0.2
5	Copper	CU 35 um	0.035
	Prepreg	PP FR4 = 0,100 mm	0.1
6	Copper	CU 35 um	0.035
	CORE	IL 0,20	0.2
7	Copper	CU 35 um	0.035
	Prepreg	PP FR4 = 0,100 mm	0.1
8	Copper	CU 35 um	0.035
	CORE	IL 0,20	0.2
9	Copper	CU 35 um	0.035
	Prepreg	PP FR4 = 0,100 mm	0.1
10	Copper	CU 35 um	0.035
	Soldermask	SM = 0,015 mm	0.015